

ABSTRACT

WAFER PROCESSING METHOD

Disclosed herein is a wafer processing method including a frame supporting step of attaching the back side of a wafer to an adhesive tape supported at its peripheral portion to an annular frame having an inside opening in such a manner that the wafer is set in the inside opening closed by the adhesive tape, thereby supporting the wafer through the adhesive tape to the annular frame. The wafer processing method further includes a shield tunnel forming step of holding the wafer on a chuck table in the condition where the front side of the wafer faces the upper surface of the chuck table, and next applying a laser beam through the adhesive tape to the back side of the wafer in an area corresponding to each division line, the laser beam having a transmission wavelength to the wafer and the adhesive tape, thereby forming a plurality of shield tunnels arranged along each division line, each shield tunnel extending from the front side of the wafer to the back side thereof, each shield tunnel being composed of a fine hold and an amorphous region formed around the fine hole for shielding the fine hole.

(Figure 3A)